

Abstract

An electronic module that operates at various radio frequency standards is provided. The module includes a first integrated circuit die formed in a first semiconductor substrate and manufactured using a first semiconductor process. Disposed within the first integrated circuit is the first signal conditioning circuit for performing a function and the first and second ancillary circuits. The first ancillary circuit electrically coupled to the first signal conditioning circuit for use by the first signal conditioning circuit during operation thereof. The second ancillary circuit is for other than being used by the first signal conditioning circuit during operation thereof since the second integrated circuit die is electrically coupled to the second ancillary circuit and formed in the second semiconductor substrate and co-located with the first integrated circuit within the module. The second integrated circuit die benefits from the operation of the second ancillary circuit for functioning thereof for performing a similar function to the first signal conditioning circuit.